g	GE Energy	Functional Testing Specification	
Parts & Repair Services Louisville, KY		LOU-GEF-550TX Print Circuit Boards	
	Test Procedure for all 550TX Cont	rol's Printed Circuit Boards.	
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<b>DATE</b> 03/26/2008	DATE	DATE	3/28/2008

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Functional test procedure for all 550TX Control PCBs

#### SCOPE

1.1 This specification provides test requirement for testing of printed circuits boards that are used in GE Mark Century 550TX Control.

#### **STANDARDS OF QUALITY**

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

### **APPLICABLE DOCUMENTS**

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.

3.1.1 GEK-25242G **Diagrams** 3.1.2 NEC-1029I **Schematic** 3.1.3 ProTrack 1 Model 10/20 **User's Manual** 

#### **ENGINEERING REQUIREMENTS**

- 4.1 Description
- 4.2 This Test is for the Testing of Printed Circuit Boards that are used in 550TX Lathe Control. Each PCB will have its own Schematic Diagram and board description.
- 4.3 Equipment Cleaning
  - Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to the local documented procedures for cleaning guidelines.

#### **Equipment Inspection**

5.1.1 Equipment should be visually inspected for any defects prior to applying power.

This inspection should include the following as a minimum:

- 5.1.1.1 Wires broken or cracked
- **5.1.1.2** Terminal strips / connectors broken or cracked
- **5.1.1.3** Loose wires
- 5.1.1.4 Components visually damaged
- 5.1.1.5 Capacitors leaking
- 5.1.1.6 Solder joints damaged or cold
- 5.1.1.7 Circuit board burned or de-laminated
- 5.1.1.8 Printed wire runs burned or damaged

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# 6. **EQUIPMENT REQUIRED**

**6.1** The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1	Huntron ProTrack 1	Component Tester.
1	Huntron ProTrack 1 Scanner	Component Scanner
1	Computer with MS Windows	Huntron Software Test Program
1	Multimeter	Fluke 77 or equivalent

### 7. TESTING PROCESS

- 7.1 Turn on Huntron ProTrack 1 and Scanner
- 7.2 Bring up Huntron Workstation for Windows on Computer
- 7.3 Select 550MC/T in System
- 7.4 Select the Part Number of the board that is to be tested
- 7.5 Start at the first component in the list to be tested. See Note
- **7.6** Scan that component if it passes move on through the list, if the component fails analyze fault by using the board's **Schematic** to troubleshoot the fault, then correct the fault (replaced bad component) and rescan the component, if it passes proceed to next Component.
- 7.7 When all components are scanned and passed the testing of the board is complete.

NOTE \*\* Not all Component will passed the Huntron Scan Test. You will have to analyze each component that failed to see if is a component failure or if the failure is cause by different type (SN or DM) or a different manufacture's IC in the circuit. This is not a Fail/Pass Test you will have to use you Technical Knowledge to decide if the Component and circuit is good.

\*\*\*TEST COMPLETE \*\*\*